

PATENT ASSIGNMENT

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| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT |
| CONVEYING PARTY DATA | |
| Name | Execution Date |
| Guo Cheng LIAO | 09/17/2008 |
| RECEIVING PARTY DATA | |
| Name: | ADVANCED SEMICONDUCTOR ENGINEERING, INC. |
| Street Address: | NO. 26, CHIN 3RD RD., NANTZE EXPORT PROCESSING ZONE |
| City: | KAOHSIUNG |
| State/Country: | TAIWAN |
| PROPERTY NUMBERS Total: 1 | |
| Property Type | Number |
| Application Number: | 12473806 |
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| NAME OF SUBMITTER: | Ayesha Wilson |
| Total Attachments: 1 source=Assignment#page1.tif | |

OP \$40.00 12473806

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

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|---------------------------|-----------|
| (1) <u>Guo Cheng LIAO</u> | (4) _____ |
| (2) _____ | (5) _____ |
| (3) _____ | (6) _____ |

who have made a certain new and useful invention, hereby sell, assign and transfer unto

Advanced Semiconductor Engineering, Inc.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

CIRCUIT BOARD WITH BURIED CONDUCTIVE TRACE FORMED THEREON AND METHOD FOR MANUFACTURING THE SAME

for which an application for United States Letters Patent was filed on _____, and identified by United States Serial No. _____; or

(a) for which an application for United States Letters Patent was executed on September 17, 2008,

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside our signatures:

| INVENTORS | DATE SIGNED |
|--|---------------------------|
| 1) Signature: <u>Guo Cheng Liao</u> Name: <u>Guo Cheng LIAO</u> | <u>September 17, 2008</u> |
| 2) Signature: _____ Name: _____ | _____ |
| 3) Signature: _____ Name: _____ | _____ |
| 4) Signature: _____ Name: _____ | _____ |
| 5) Signature: _____ Name: _____ | _____ |
| 6) Signature: _____ Name: _____ | _____ |